

RKS1510DKK

Silicon Epitaxial Planar Diode for UHF/VHF tuner Band Switch

REJ03G0538-0100 Rev.1.00 Feb 23, 2005

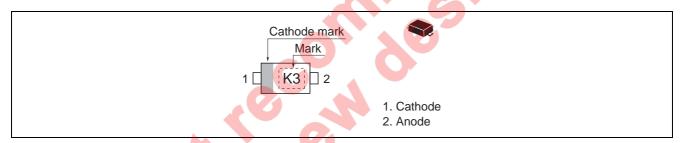
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward resistance. (rf = $0.7 \Omega \text{ max}$)
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKS1510DKK	K3	SFP	PUSF0002ZB-A
			(SFP)

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	35	V
Power dissipation	Pd	150	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

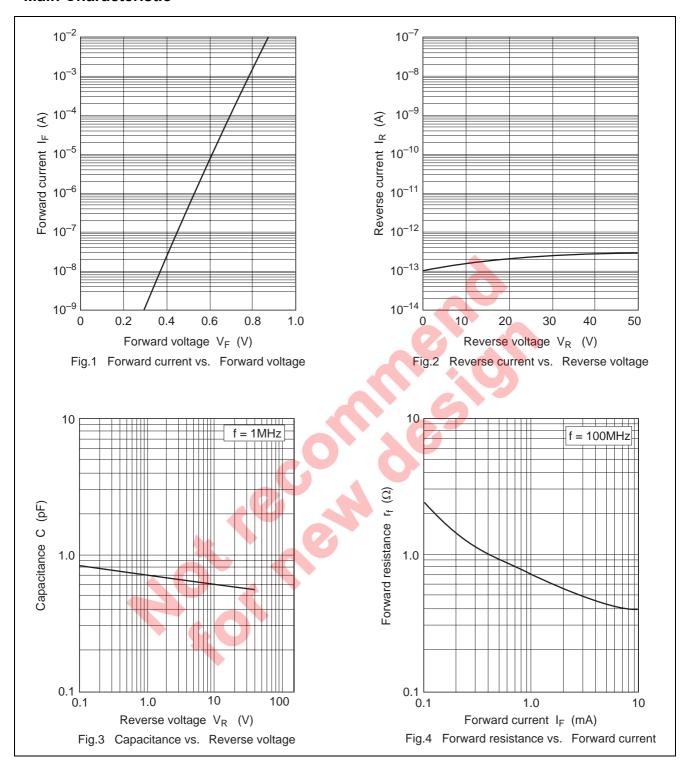
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R			50	nA	V _R = 25 V
Forward voltage	V _F	_	_	1.0	V	J _F = 10 mA
Capacitance	С	_	_	0.8	pF	V _R = 6 V, f = 1 MHz
Forward resistance	r _f	_	_	0.7	Ω	I _F = 2 mA, f = 100 MHz

Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

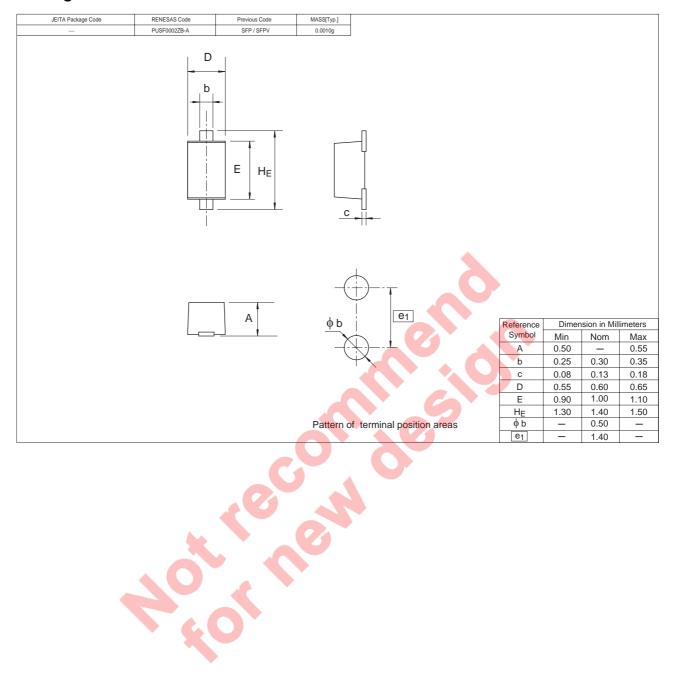
2. The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.



Main Characteristic



Package Dimensions



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